













- ► PTH/THT Lamp
- ▶ 8mm Round 11.0t
- ► True Green (525nm)

N0G32L14Z





### **FEATURES:**



8mm Round Lamp Compliant

Forward Current: 20mA Forward Voltage (typ.): 3.2V

Luminous Intensity (typ.): 30000mcd@20mA

Colour: True Green

Dominant Wavelength (typ.): 525nm

Viewing Angle: 20°

**Materials:** 

Die: InGaN

Resin: Epoxy (Water Clear)

Operating Temperature: -40~+85°C

Storage Temperature: -40~+100°C

**Grouping Parameters:** 

Forward voltage

Luminous intensity

Dominant wavelength

Soldering Methods: Hand; Soldering Heat (DIP)

Packing: max.500pcs/bulk

### **APPLICATIONS:**

- Indicator
- Signal
- 3C Application



## **CHARACTERISTICS:**

# Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	IF	30	mA
Peak Forward Current Duty 1/10@1KHz	I <sub>FP</sub>	100	mA
Reverse Current @5V	IR	10	μΑ
Reverse Voltage	V <sub>R</sub>	5	V
Power Dissipation	P <sub>D</sub>	85	mW
Electrostatic Discharge	ESD	2000	V
Operating Temperature	$T_OPR$	-40~+85	°C
Storage Temperature	T <sub>STG</sub>	-40~+100	°C

# Electrical & Optical Characteristics (Ta=25°C)

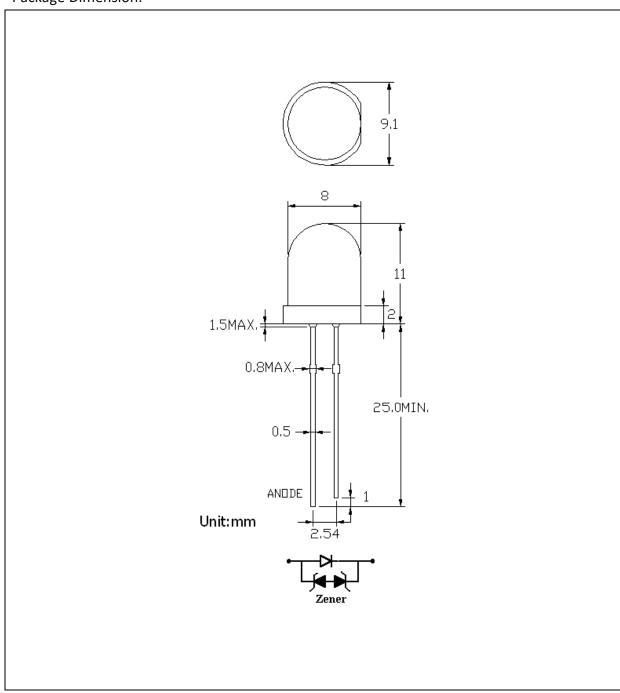
Darameter	Symbol	Values			Linit	Test
Parameter		Min.	Тур.	Max.	Unit	Condition
Forward Voltage	V <sub>F</sub>	2.9	3.2	3.5	V	I <sub>F</sub> =20mA
Luminous Intensity	Iv	25000	30000	42000	mcd	I <sub>F</sub> =20mA
Dominant Wavelength	$\lambda_{D}$	517	525	530	nm	I <sub>F</sub> =20mA
Peak Wavelength	$\lambda_{ extsf{P}}$		525		nm	I <sub>F</sub> =20mA
Spectral Line Half Bandwidth	Δλ		36		nm	I <sub>F</sub> =20mA
Viewing Angle	2θ <sub>1/2</sub>		20		deg	I <sub>F</sub> =20mA

<sup>1.</sup> Luminous intensity (I<sub>V</sub>)  $\pm 15\%$ , Forward Voltage (V<sub>F</sub>)  $\pm 0.1$ V, Viewing angle( $2\theta_{1/2}$ )  $\pm 5\%$ 



## **OUTLINE DIMENSION:**

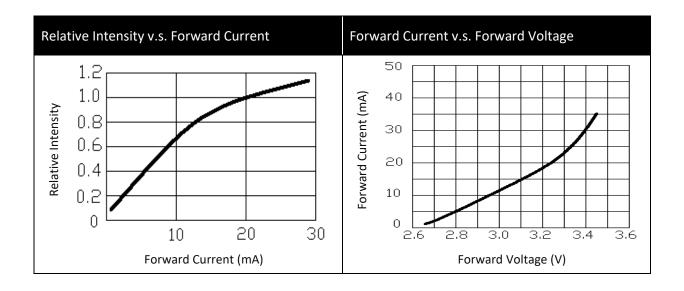
## Package Dimension:

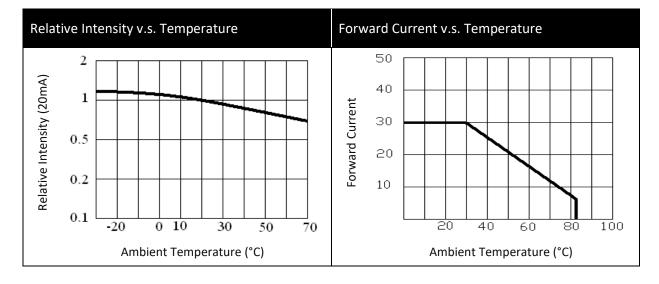


- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.2mm, unless otherwise noted.



### **ELECTRO-OPTICAL CHARACTERISTICS:**





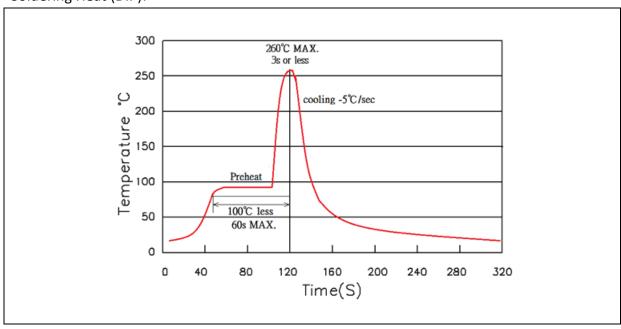


### **RECOMMENDED SOLDERING PROFILE:**

## Hand Solder (Solder Iron):

- Temperature at tip of iron: 350°C Max.
- Soldering Time: 3 seconds ± 1 sec.

## Soldering Heat (DIP):



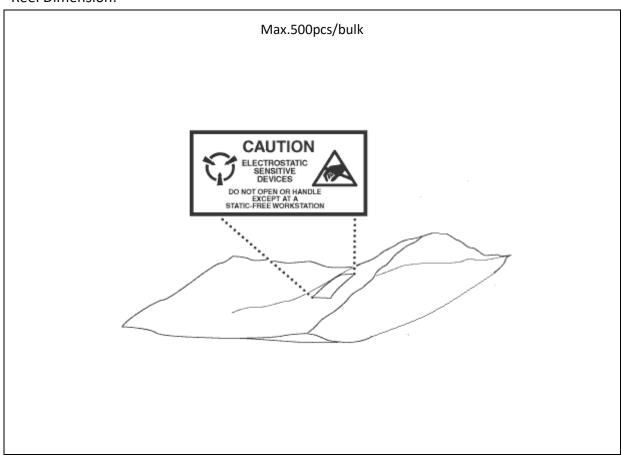
#### Note:

- 1. Maximum reflow soldering: 1 time.
- 2. Before, during, and after soldering, should not apply stress on the components and PCB board.



## **PACKING SPECIFICATION:**

### Reel Dimension:





#### **PRECAUTIONS OF USE:**

#### Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a year. Otherwise, they should be kept in a damp-proof box with descanting agent <10% R.H. and apply baking before use.

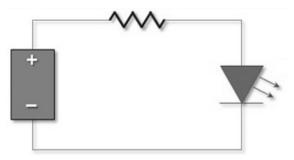
#### Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

• 60±5°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

### **Testing Circuit:**



Must apply resistor(s) for protection (over current proof).

### Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

## ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



# **REVISION RECORD:**

Version	Date	Summary of Revision
A1.0	05/04/2023	Datasheet set-up.
A1.1	13/12/2023	Revise storage condition.